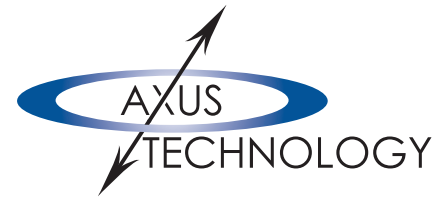


IPEC 676 CMP Tool with Orbital Motion



Your source for leading-edge
surface processing solutions



The IPEC 676 is a Dry-in/Wet-out automated CMP system best suited for metal CMP but can also be used for dielectric CMP processes. It has one of the industry's smallest footprints. The 676 is designed to improve yields by use of an orbital polishing motion rather than conventional rotational CMP techniques. This leads to improved wafers per square foot in the fab.

FEATURES

- Four wafer planarizers (polishing modules)
- Cassette tilter load/unload station
- Advanced pad motion control
- Advanced through-the-pad slurry distribution method - High speed polish drive (0-600 RPM)
- Closed loop delta P control
- Endpoint detection system
- Stainless steel polish bell
- Dual pad conditioning systems
- Upgraded 500MHz Pentium

DIMENSIONS		FACILITIES	
mm	2083W x 1753D x 2591H	Power	120/208 VAC WYE 3 Phase, 60 Hz, 60 Amps Max.
Inches	82W x 69D x 102H		
		DI Water	50psi / 5gpm